

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Takahiko IDO	12/21/2007
Chizuru KASAI	12/21/2007
RECEIVING PARTY DATA	
Name:	IBIDEN CO., LTD.
Street Address:	1 Kandacho, 2-chome, Ogaki-shi
City:	Gifu
State/Country:	JAPAN
Postal Code:	503-8604
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11925394
CORRESPONDENCE DATA	
Fax Number:	(703)519-9958
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	703-519-9953
Email:	jmori@dcpatent.com
Correspondent Name:	Masayasu Mori
Address Line 1:	918 PRINCE STREET
Address Line 4:	Alexandria, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	01098_1038
NAME OF SUBMITTER:	Junko Mori
Total Attachments: 2 source=01098-1038_Assignment#page1.tif source=01098-1038_Assignment#page2.tif	

OP \$40.00 11925394

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PATENT
REEL: 020326 FRAME: 0616

Attorney Docket No.: 01098_1038
Client Docket No.: IB1180US

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we the undersigned, Takahiko IDO, and Chizuru KASAI, hereby sell, assign, and transfer to IBIDEN CO., LTD., a corporation of Japan, having a principal place of business at 1, Kandacho 2-chome, Ogaki-shi, Gifu 503-8604 JAPAN ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements that are disclosed in the application for the United States patent, entitled:

HONEYCOMB STRUCTURE AND METHOD FOR MANUFACTURING THE SAME

- ☐ which has been executed by the undersigned concurrently herewith,
☒ which was filed on October 26, 2007 and assigned Serial No. 11/925,394

and in to said application and all divisional, continuing, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application;

agree that said Assignee may apply for and receive a patent or patents for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all assignments and powers of attorney; communicate to said Assignee, its successors, assigns, and representatives all facts known to the undersigned relating to said improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or representatives in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Each Inventor: Please Sign and Date Below:

DEC. 21. 2007

Date

Takahiko Ido

Name: Takahiko IDO

DEC. 21. 2007

Date

Chizuru KASAI

Name: Chizuru KASAI